

## 1200V SiC N-Channel MOSFET

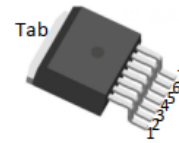
### DESCRIPTION :

- High Speed Switching with Low Capacitances
- High Blocking Voltage with Low  $R_{DS(ON)}$
- Easy to Parallel
- Simple to Drive
- RoHS compliant.

$V_{DS}$	1200V
$I_D (T_C=25^\circ\text{C})$	46A
$R_{DS(ON\_Typ.)@V_{GS}=18V}$	59m $\Omega$

### TYPICAL APPLICATIONS :

- Power Factor Correction Modules
- Switch Mode Power Supplies
- DC-AC Inverters
- High Voltage DC-DC Converters



TO-263-7L

### MAXIMUM RATINGS (at $T_J = 25^\circ\text{C}$ , unless otherwise specified)

Characteristic	Condition	Symbol	Value	Unit
Drain-Source Voltage		$V_{DS}$	1200	V
Continuous Drain Current	$T_C=25^\circ\text{C}$ $T_C=100^\circ\text{C}$	$I_D$	46 35	A
Peak Drain Current	Pulse width $t_p$ limited by $T_{jmax}$	$I_{DM}$	105	A
Gate-Source Voltage		$V_{GSmax}$	-8/+22	V
Recommend Gate-Source Voltage		$V_{GSop}$	-4/+18	V
Power Dissipation	$T_C=25^\circ\text{C}$ $T_C=100^\circ\text{C}$	$P_{TOT}$	263 131	W
Operation Junction temperature		$T_j$	-40~+175	$^\circ\text{C}$
Storage temperature		$T_{STG}$	-40~+175	$^\circ\text{C}$

### THERMAL CHARACTERISTICS

Characteristic	Condition	Symbol	Typical	Unit
Thermal resistance, junction - case		$R_{th(j-c)}$	0.57	$^\circ\text{C/W}$

**ELECTRICAL CHARACTERISTICS (at  $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)**

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage VGS = 0V, ID = 100 $\mu$ A	$V_{(BR)DSS}$	1200			V
Zero Gate Voltage Drain Current VDS = 1200 V, VGS = 0 V	$I_{DSS}$		1		$\mu$ A
Gate-Source Leakage Current VGS = 18V, VDS = 0V	$I_{GSS}$			250	nA
Gate-Source Threshold Voltage VDS = VGS, ID = 5mA $T_j=25^\circ\text{C}$ VDS = VGS, ID = 5mA $T_j=150^\circ\text{C}$ VDS = VGS, ID = 5mA $T_j=175^\circ\text{C}$	$V_{GS(th)}$	2.0	2.8 2.2 2.1	4.0	V
Drain-Source On-State Resistance VGS = 18V, ID = 20A $T_j=25^\circ\text{C}$ VGS = 18V, ID = 20A $T_j=150^\circ\text{C}$ VGS = 18V, ID = 20A $T_j=175^\circ\text{C}$	$R_{DS(on)}$		59 81 90		m $\Omega$
Internal Gate Resistance f=1MHz	$R_{G(INT)}$		0.98		$\Omega$
Input capacitance f=1MHz, VDS=1000 V, VGS=0 V	$C_{iss}$		2451		pF
Output capacitance f=1MHz, VDS=1000 V, VGS=0 V	$C_{oss}$		79		pF
Reverse transfer capacitance f=1MHz, VDS=1000 V, VGS=0 V	$C_{rss}$		6		pF
Total Gate Charge VDS= 800V, ID= 20A, VGS= -4/18V	$Q_G$		103		nC
Gate to Source Charge VDS= 800V, ID= 20A, VGS= -4/18V	$Q_{GS}$		29		nC
Gate to Drain Charge VDS= 800V, ID= 20A, VGS= -4/18V	$Q_{GD}$		36		nC
Turn-on Delay Time VDD=800 V, ID=20A, VGS= -4/18V, RG=0 $\Omega$	$t_{d(ON)}$		14		ns
Rise Time VDD=800 V, ID=20A, VGS= -4/18V, RG=0 $\Omega$	$t_r$		10		ns
Turn-off Delay Time VDD=800 V, ID=20A, VGS= -4/18V, RG=0 $\Omega$	$t_{d(OFF)}$		22		ns
Fall Time VDD=800 V, ID=20A, VGS= -4/18V, RG=0 $\Omega$	$t_f$		9		ns

Turn-on Switching Energy VDD=800 V, ID=20A, VGS= -4/18V, RG=0Ω	$E_{(ON)}$		125		μJ
Turn-off Switching Energy VDD=800 V, ID=20A, VGS= -4/18V, RG=0Ω	$E_{(OFF)}$		25		μJ

Body Diode

ELECTRICAL CHARACTERISTICS (at  $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Diode Forward Voltage VGS = -4V, ISD = 20A $T_J=25^\circ\text{C}$ VGS = -4V, ISD = 20A $T_J=175^\circ\text{C}$	$V_{SD}$		4.6 4.2		V
Continuous Diode Forward Current VGS = -4V, $T_c=25^\circ\text{C}$ VGS = -4V, $T_c=100^\circ\text{C}$	$I_S$		43 23		A
Revers Recovery Time VR=800 V, ISD=20A, VGS= -4V, di/dt = 3830A/us	Trr		56		ns
Revers Recovery Charge VR=800 V, ISD=20A, VGS= -4V, di/dt = 3830A/us	Qrr		76		nC
Peak Revers Recovery Current VR=800 V, ISD=20A, VGS= -4V, di/dt = 3830A/us	$I_{rrm}$		13		A

Typical Characteristics

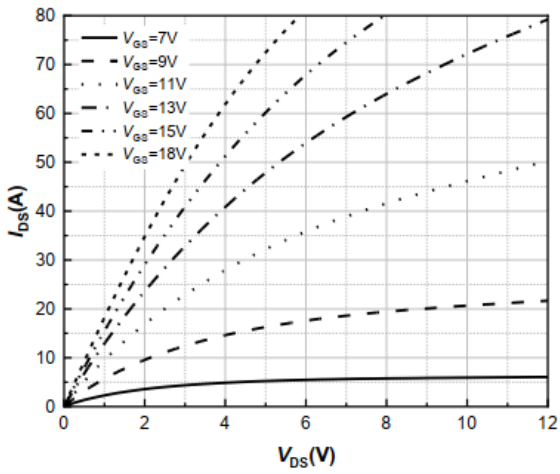


Figure 1. Typical output characteristics (Tj=25°C)

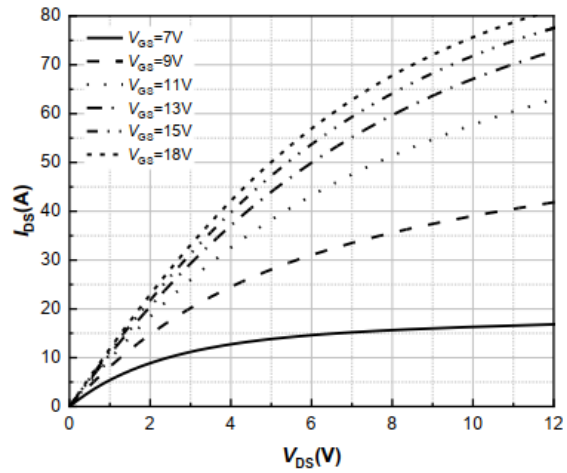


Figure 2. Typical output characteristics (Tj=175°C)

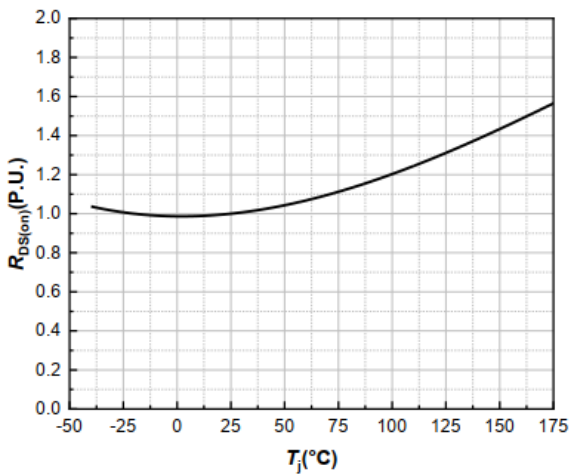


Figure 3. Normalized Resistance v/s Temperature

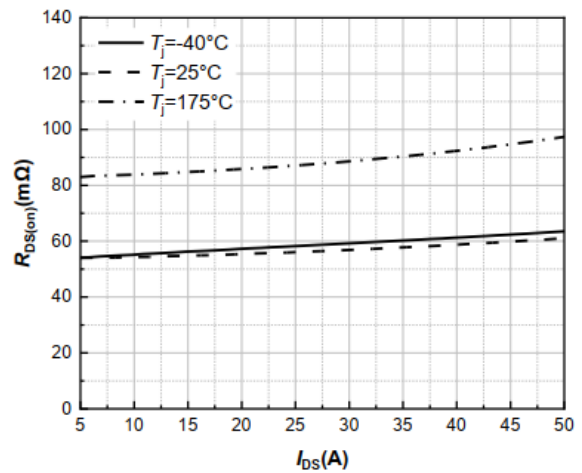


Figure 4. On-Resistance vs. Drain Current For Various Temperatures

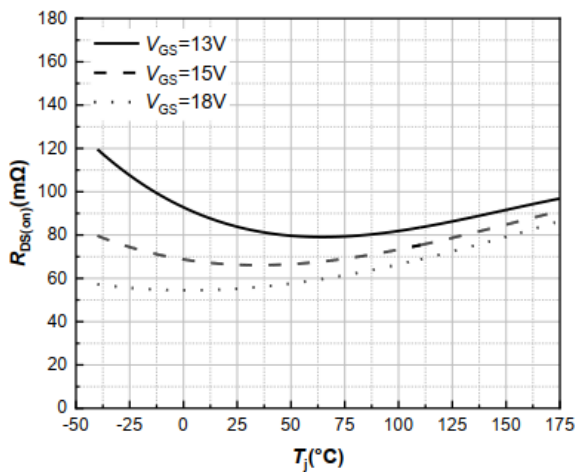


Figure 5. On-Resistance vs. Temperature For Various Gate Voltage

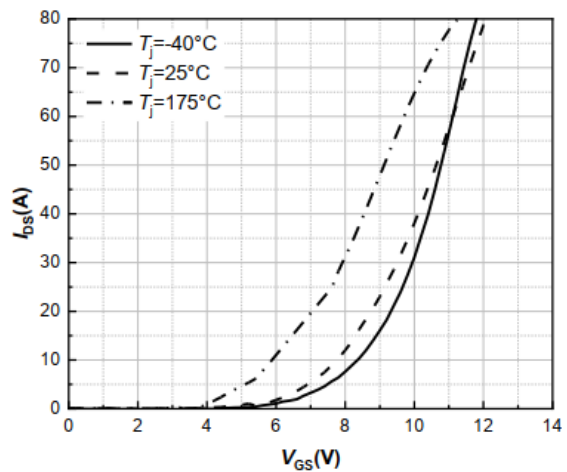


Figure 6. Transfer Characteristic for Various Junction Temperatures VDS=20V

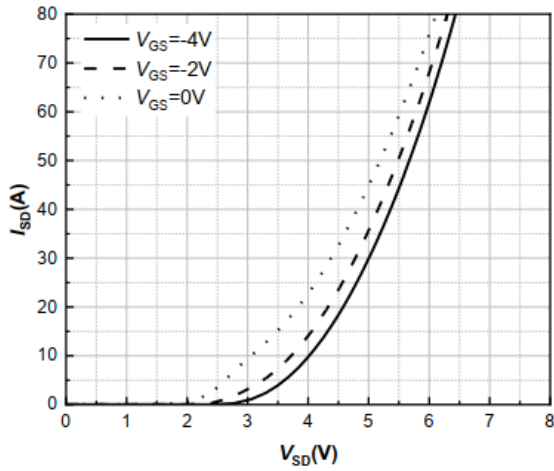


Figure 7. Body Diode Characteristic  $T_j=25^\circ\text{C}$

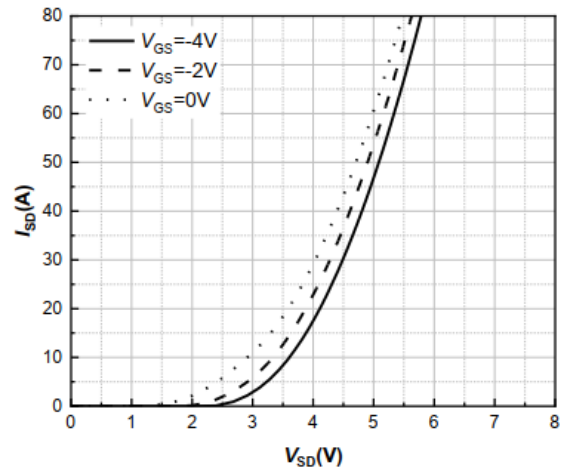


Figure 8. Body Diode Characteristic  $T_j=175^\circ\text{C}$

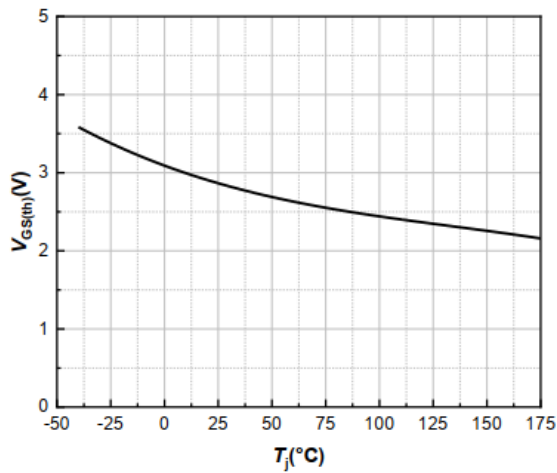


Figure 9. Threshold Voltage vs. Temperature

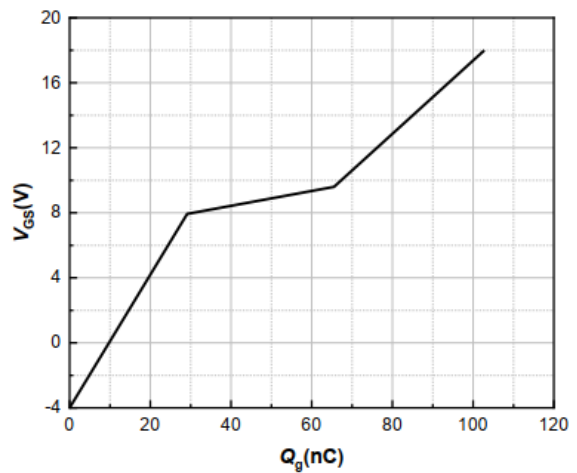


Figure 10. Gate Charge Characteristics

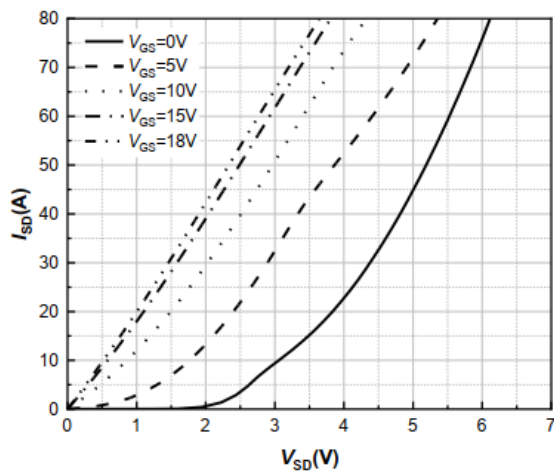


Figure 11. 3rd Quadrant Characteristic  $T_j=25^\circ\text{C}$

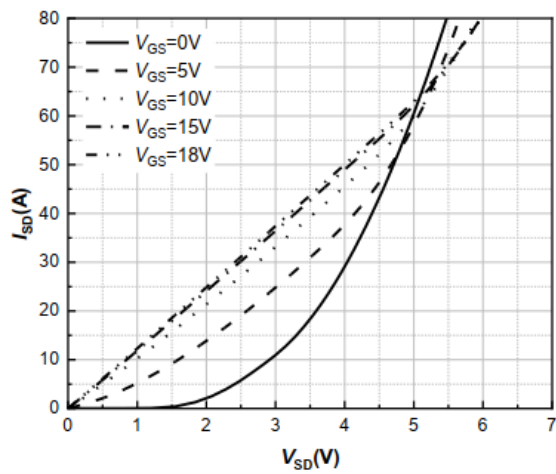


Figure 12. 3rd Quadrant Characteristic  $T_j=175^\circ\text{C}$

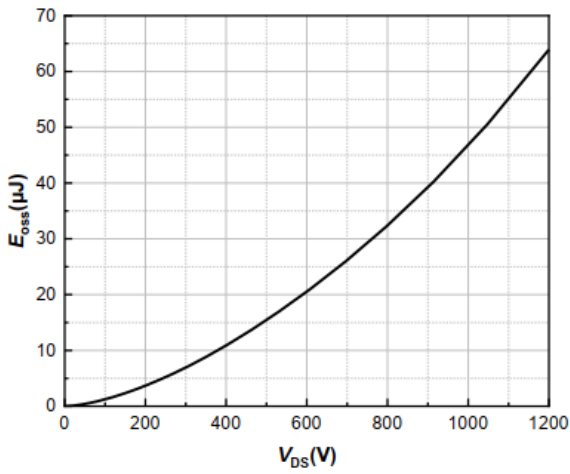


Figure 13. Output Capacitor Stored Energy

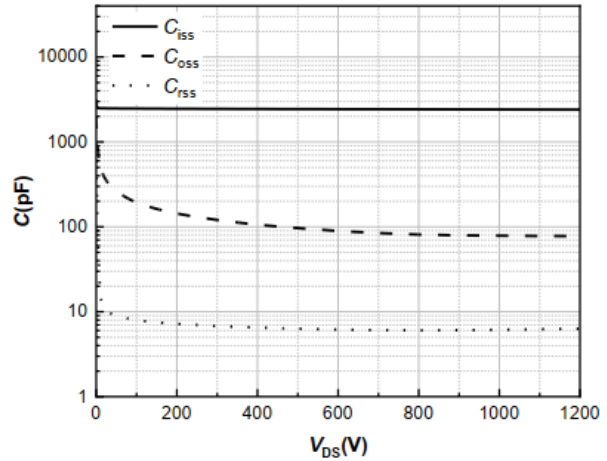


Figure 14. Capacitances vs. Drain-Source

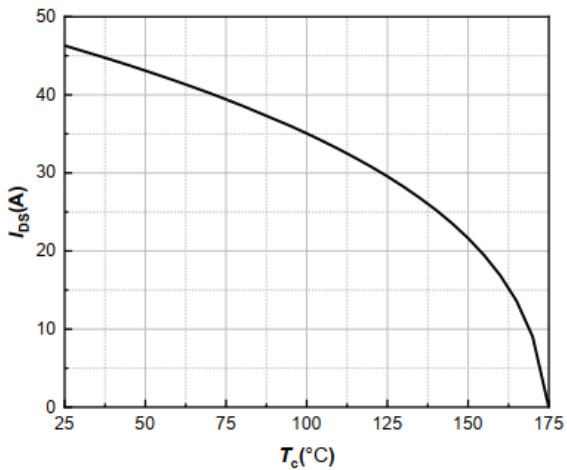


Figure 15. Continuous Drain Current Derating vs. Case Temperature

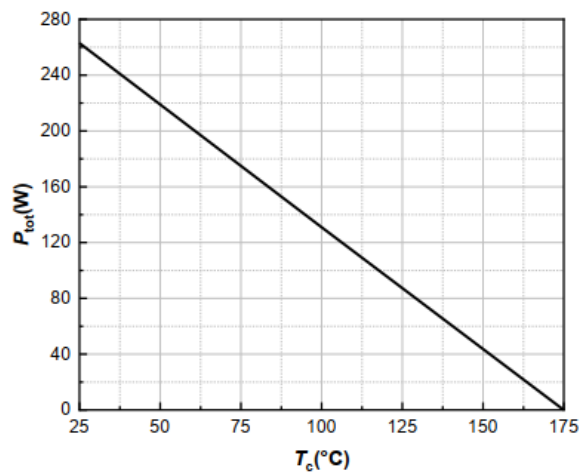


Figure 16. Maximum Power Dissipation Derating vs. Case Temperature

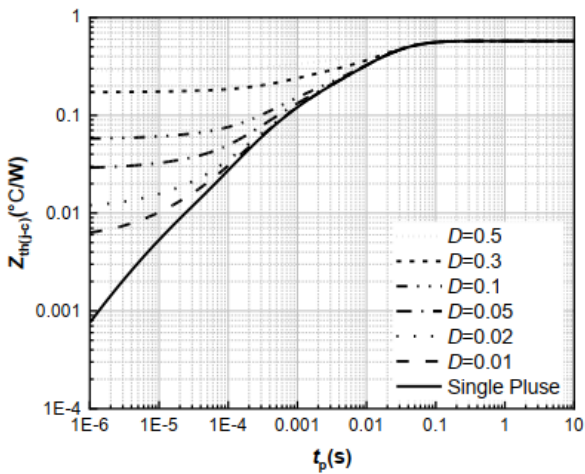


Figure 17. Transient Thermal Impedance

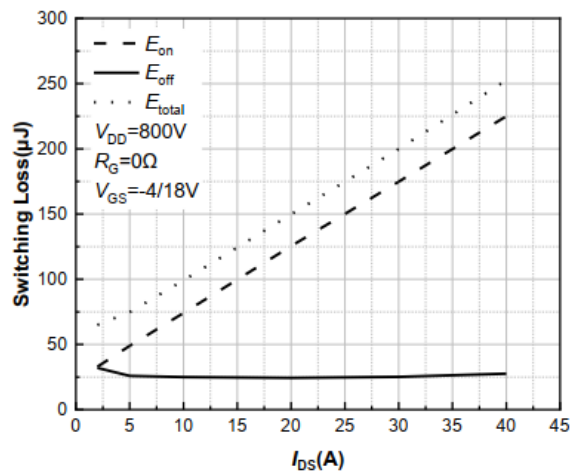


Figure 18. Clamped Inductive Switching Energy vs. Drain Current

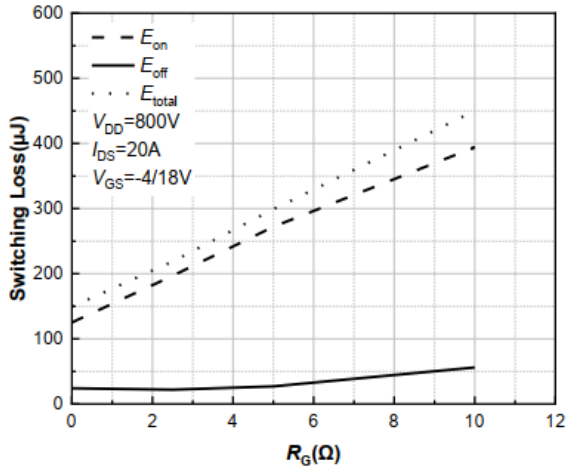


Figure 19. Clamped Inductive Switching Energy vs. RG

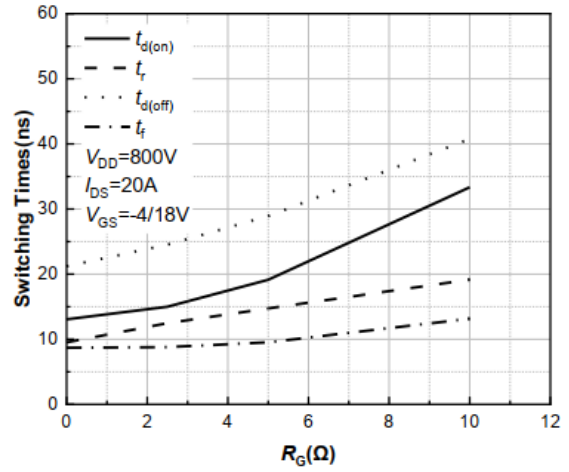


Figure 20. Switching Times vs. RG

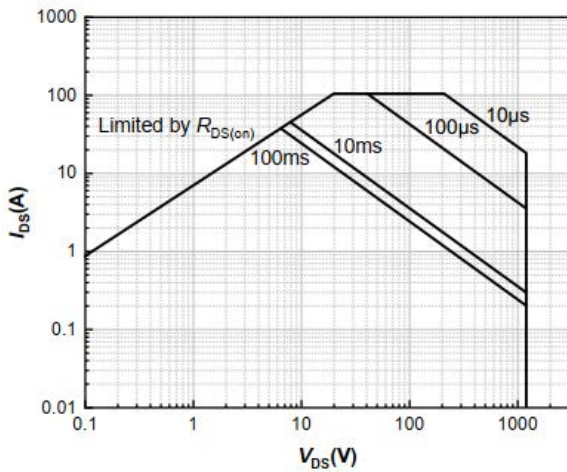
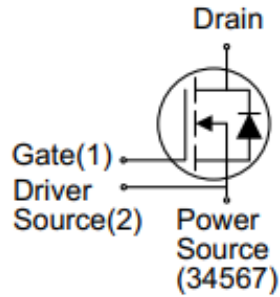
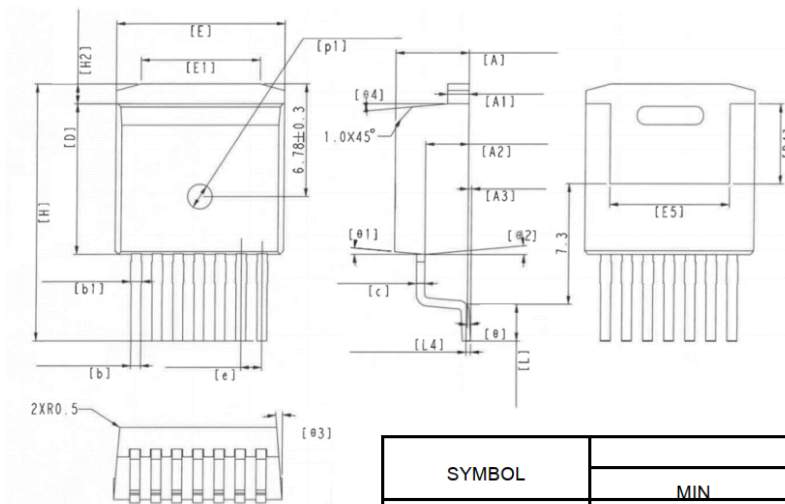


Figure 21. Safe Operating Area

- Circuit diagram



- TO-263-7L Package outlines : Dimensions in (mm)



SYMBOL	Unit: mm		
	MIN	NOM	MAX
A	4.30	4.43	4.56
A1	1.2	1.3	1.4
A2	2.45	2.60	2.75
A3	0.00	0.13	0.25
b	0.5	0.6	0.7
b1	0.6	0.7	0.9
c	0.45	0.50	0.60
D	8.93	9.08	9.23
D4	4.65	4.80	4.95
E	10.08	10.18	10.28
E1	6.5	7.0	7.5
E5	6.82	7.22	7.62
e	1.27BSC		
H	15.0	15.5	16.0
H2	0.98	1.20	1.42
L	1.9	2.2	2.5
L4	0.25BSC		
p1	1.4	1.5	1.6
theta	0°	3°	7°
theta1	3°	5°	7°
theta2	3°	5°	7°
theta3	3°	5°	7°
theta4	3°	5°	7°

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